WinWay

Your Trusted Partner in Semiconductor Testing

TWSE 6515

Investor Presentation

2025.08.15

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Company Information


Kaohsiung
Headquarter


Hsinchu
Branch Office


USA
Branch Office

- **Founded**

  2001 / 4 / 10

- **Business Operation**

  Design, manufacture, sale and service of test interface products

- **Chairman & CEO**

  Mark Wang

- **Capital Stock**

  NTD 358,501,260

- **Employees**

  1006

- **Registered Address**

  No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City, Taiwan

Agenda

Global Presence

Industry Trend

Financial Performance

R&D Innovation

WinWay
穎崴科技

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Global Presence

Global Service & Support Network

KH Spring Probe

Spring Probe
for Socket

KH Plant

Coaxial Socket
HyperSocket™

Hsinchu Plant

Vertical Probe Card
MEMS Probe Card

Suzhou Plant

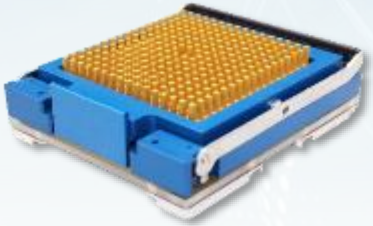
Burn-in Socket

Semiconductor Test Interface Leadership

2024

Test and Burn-in Socket Ranking

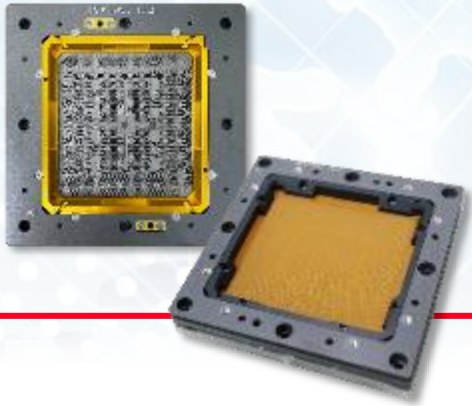
02



2024

Test Socket Ranking

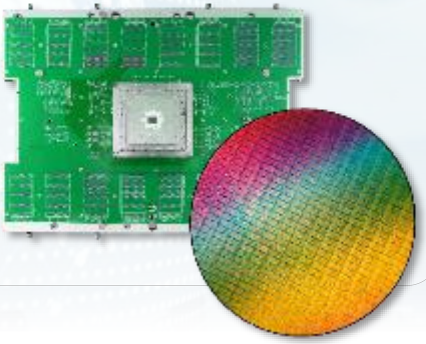
01



2024

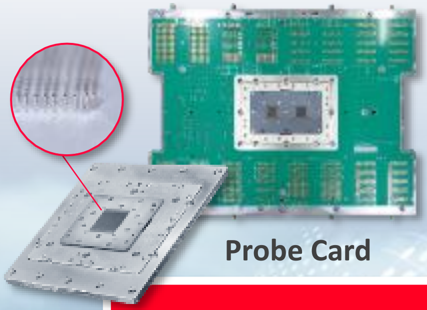
Probe Card Ranking

18



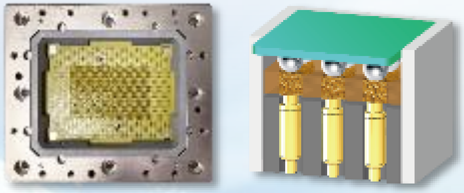
Source： Yole Intelligence, 2025/04

Total Solution for Semiconductor Test



Probe Card

Wafer Sort



Coaxial Socket & HyperSocket™

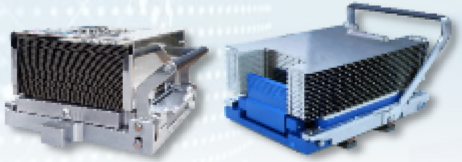
SLT & SFT

Final Test

Plastic Socket & RF Socket

Functional Burn-in

Burn-in Socket

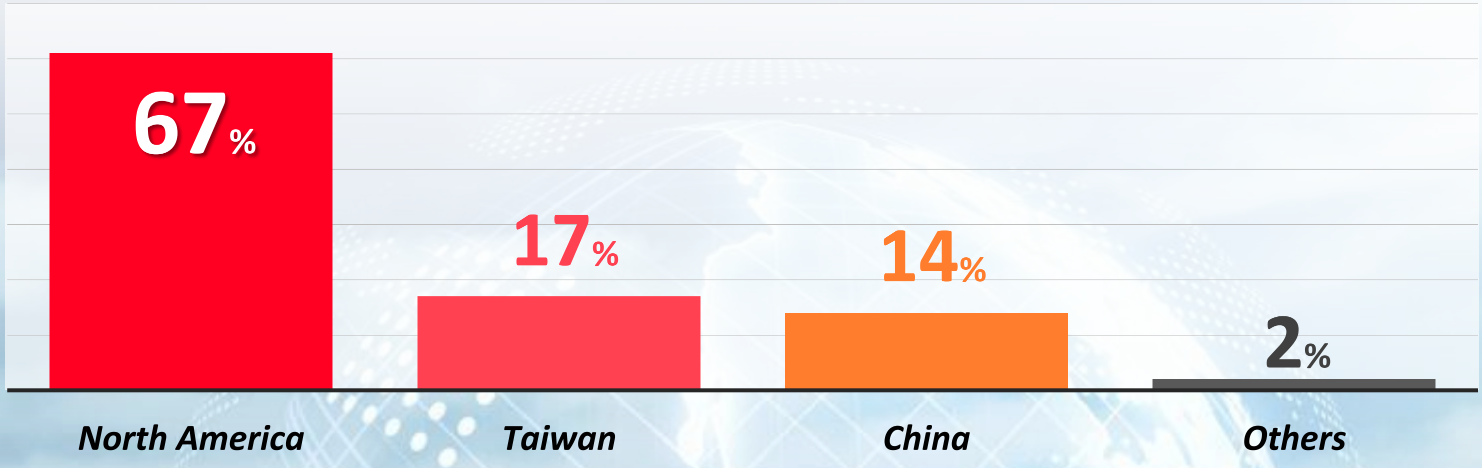


DFT **D**esign **F**or **T**esting

DFM **D**esign **F**or **M**anufacturing

Worldwide Customer

(First 5 Months of 2025)



89% Top10 Customers

- AI
- HPC
- ASIC
- AP
- CPU
- GPU

200+ Active Customers

- IC Design
- CSP
- Foundry
- IDM
- OSAT

Bolstered by Advanced Technology

Mature Node **13%**

Advanced Node **87%**

7nm (or equivalent node) and below

Automotive

Networking

IoT

DTV & STB

NAND Flash

AI

HPC

GPU

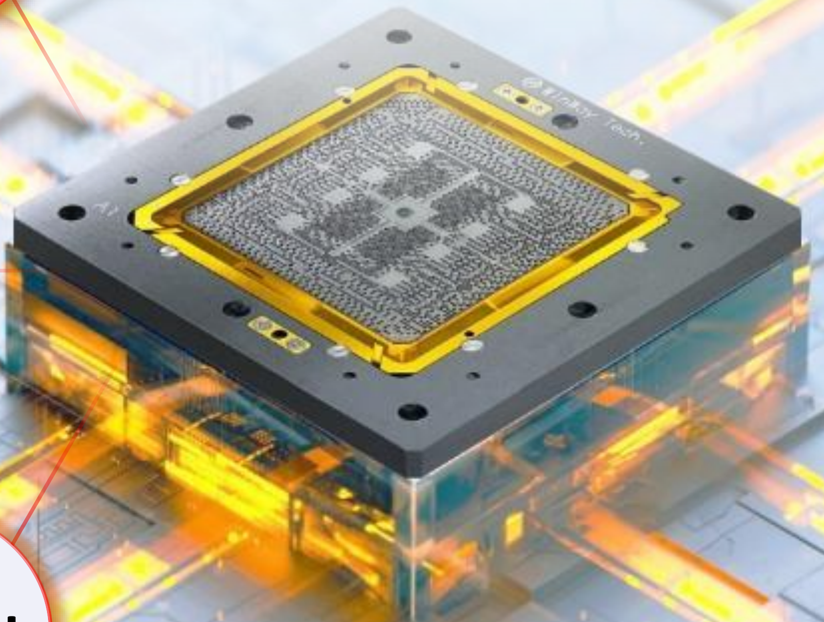
CPU

Smart Phone

High Performance Testing Driven by Advanced Packaging

- High Frequency
- High Speed
- Large Package
- High Power

- CoWoS
- CPO
- Chiplet



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Industry Trend

Driving Force for AI

AI Server

Data Center

Collaborative Robots

AI PC & Phone

Edge Computing

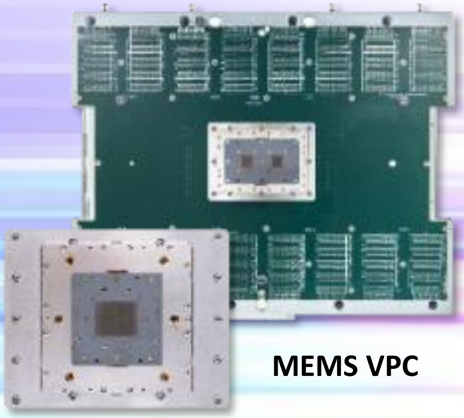
High Speed Networking

Greater Importance on Chip Probing

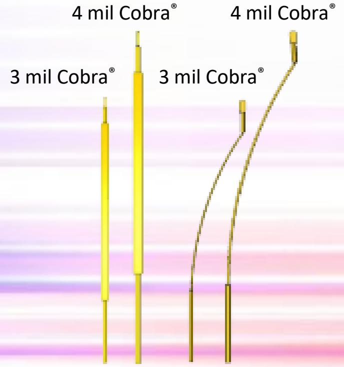
From the Shadows to the Spotlight

K.G.D Close to Known Good Die

- CoWoS
- CPO
- Chiplet



MEMS VPC

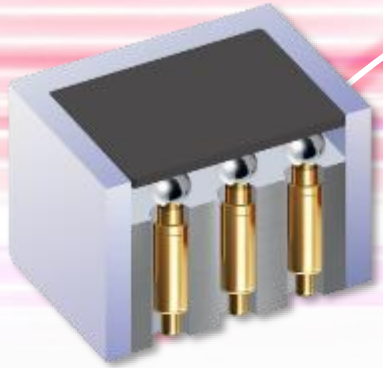


Cobra VPC

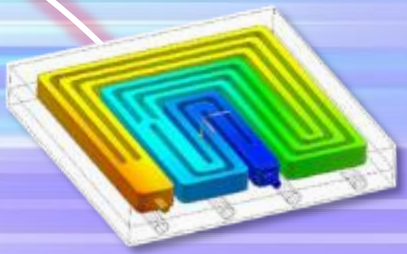
WLCSP Probe Card

Accelerated SLT Demand Driven by AI

HyperSocket™



Coaxial Socket



(Liquid Cooling)

Thermal System

2025-2030

SLT & SFT

CAGR

More than

Greater than industry growth

15%

Source：WinWay 2025

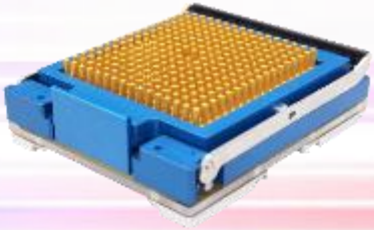
Emerging Trend Toward Functional Burn-In

Functional Burn-in

AI & HPC

Mass Production Burn-in

Automotive



Reliability Burn-in

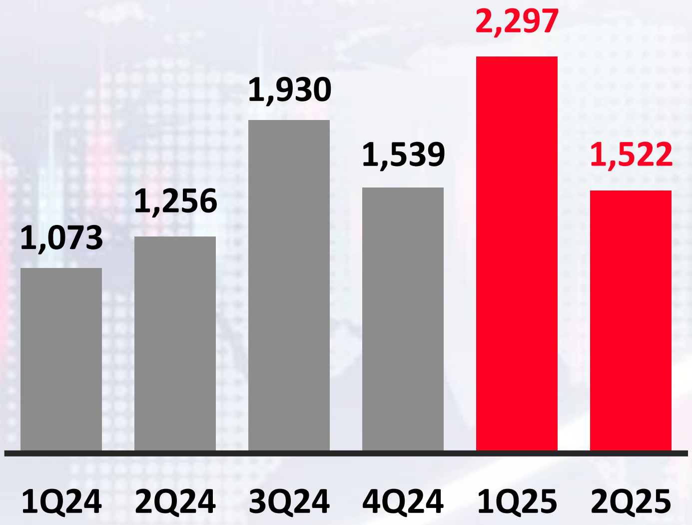
For all IC testing

Financial Performance

Revenue Trend

QUARTERLY REVENUE

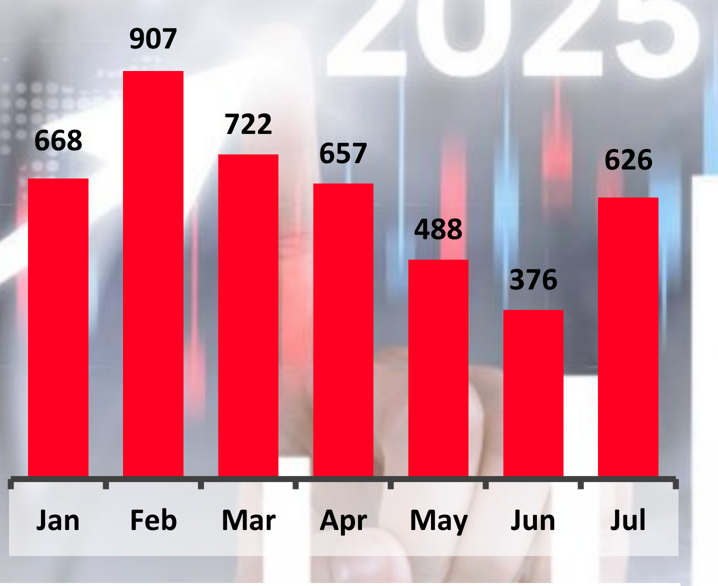
(NTD MILLION)



	1Q24	2Q24	3Q24	4Q24	1Q25	2Q25
YoY	6%	24%	96%	129%	114%	21%
QoQ	59%	17%	54%	-20%	49%	-34%

MONTHLY REVENUE

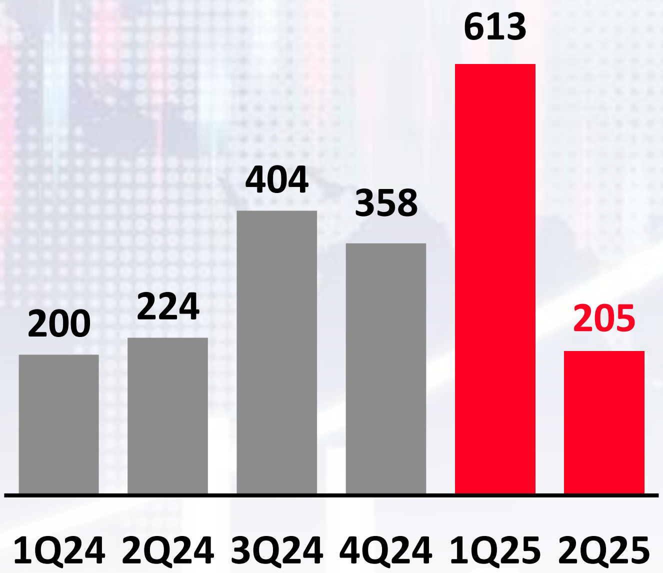
(NTD MILLION)

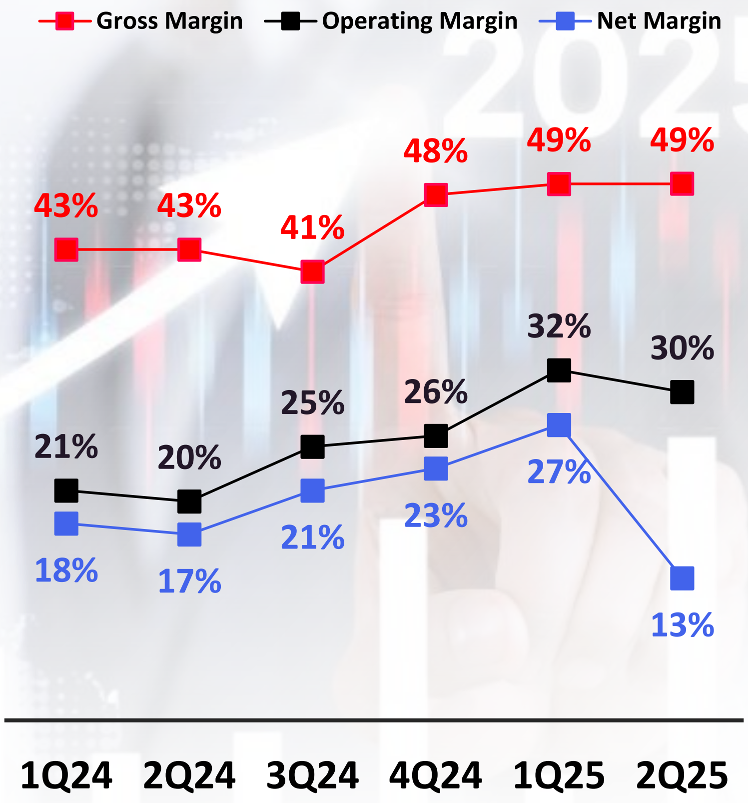


	Jan	Feb	Mar	Apr	May	Jun	Jul
YoY	82%	191%	84%	40%	37%	-12%	5%
MoM	47%	36%	-20%	-9%	-26%	-23%	66%

Profitability Trend

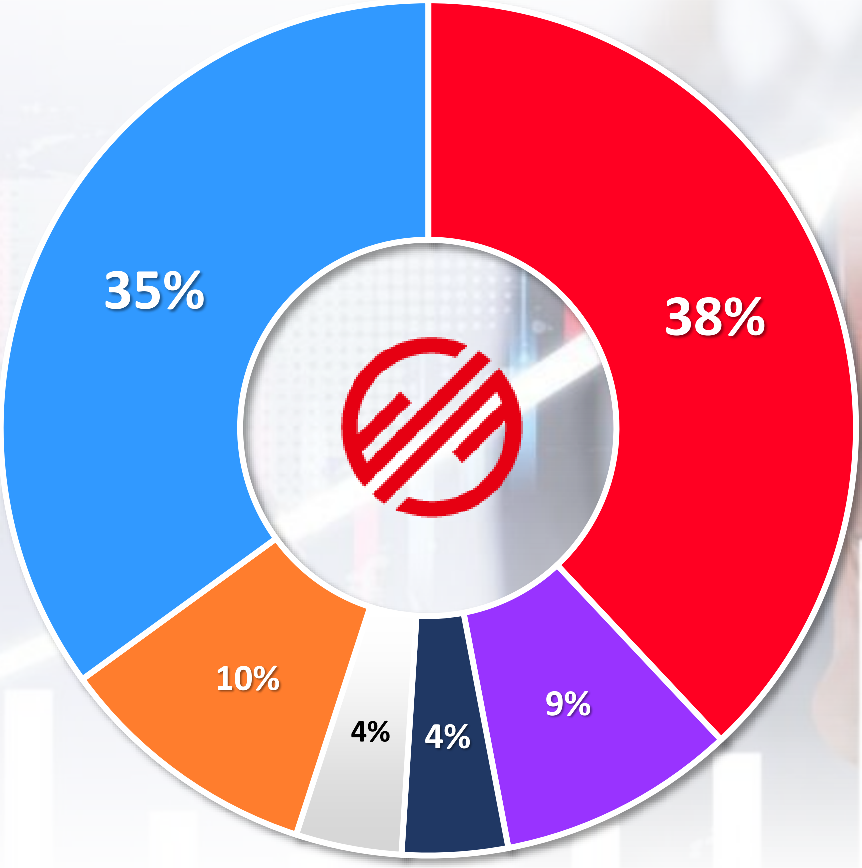
EPS	5.81	6.52	11.75	10.23	17.21	5.76


NET INCOME (NTD M)



Revenue by Product Mix

(1H 2025)



Probe Card

35%

Contact Element

10%

Others

4%

Coaxial Socket

38%

RF & Plastic Socket

9%

Burn-in Socket

4%

Revenue by End Market

(1H 2025)

HPC & AI

39 %

Coaxial Socket

HyperSocket^{TM}

PC & Gaming

37 %

HyperSocket^{TM} , Coaxial

Smart Phone

6 %

POP Plastic Socket

Networking
Auto / Others

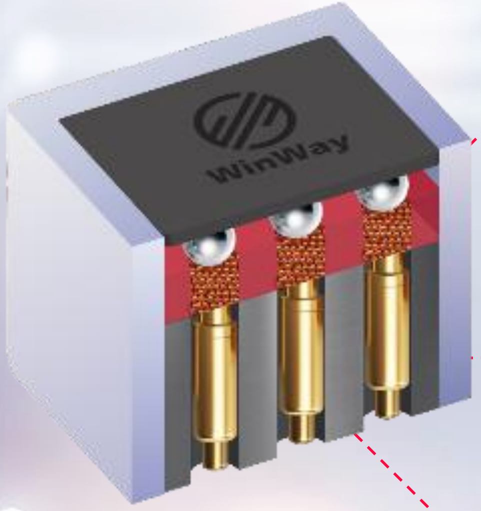
18 %

Plastic Socket

R&D Innovation

Innovative Semiconductor Test Interface Solution

WinWay HyperSocket^{TM}



Patent NO.

- TWI862047
- TWI862191
- TWI884802
- CN20570508U

Patent Pending

- USA
- Malaysia

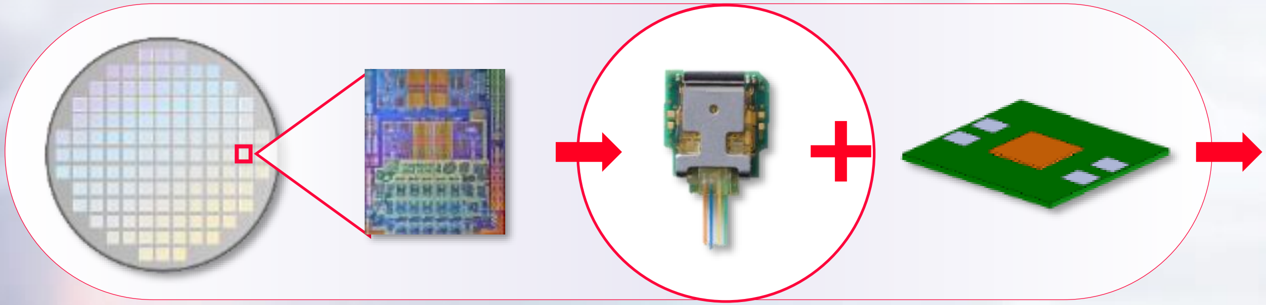
2.5D / 3D / CoWoS / CPO

Generative / Agentic / Physical AI

Collaborative Robots

Co-Packaged Optics Test Solution

Wafer Level | **Die Level** | **Package Level** | **Module Level**

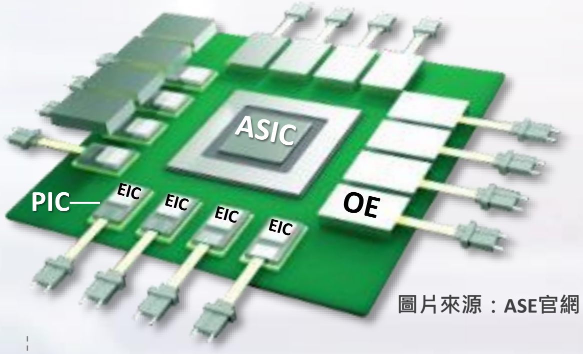


Silicon Photonic Wafer

Die

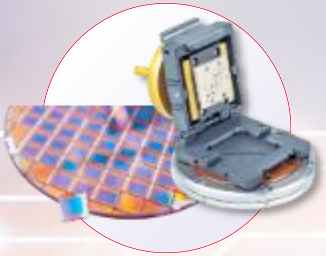
Optical Engine

CPO Substrate

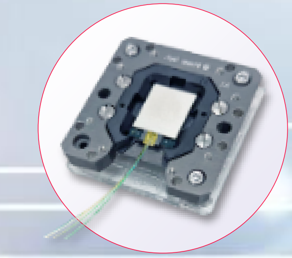


圖片來源：ASE官網

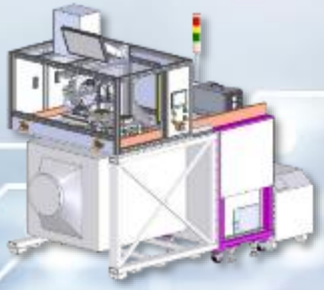
CPO Module



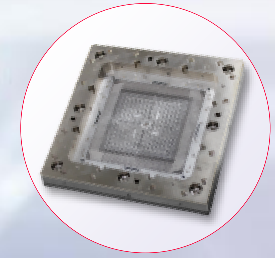
WLCSP Fine Pitch Socket
(PIC & EIC Wafer test)



Optical and Electrical Test Socket
(Optical Engine)



Double Sided Probing System



Coaxial Socket

High Power Thermal Solution

E-Flux6.0 3500W
Liquid Cooling System

SEMICON TAIWAN

2025.09.10-12

Taiwan / TaiNEX Hall 1 and 2, Taipei

SEMICON WEST

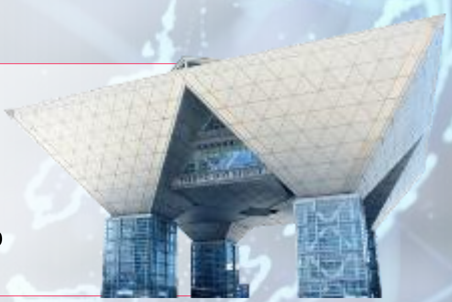
2025.10.07-09

USA / Phoenix Convention Center, Phoenix, AZ

SEMICON JAPAN

2025.12.11-13

JAPAN / Tokyo Big Sight, Tokyo



Q&A

股票代號 6515

You may contact WinWay Technology via

sales@winwayglobal.com

+886 7 361 0999 / +886 3 656 8282

www.winwayglobal.com